



Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model

[List multiple models if applicable.]

HP ProDesk 600 G3 Desktop Mini Business PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm PCA	1
Batteries	All types including standard alkaline and lithium coin or button style batteries Lithium Coin Battery on MB	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries NA	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps LED Backlight	0
Cathode Ray Tubes (CRT)	NA	0
Capacitors / condensers (Containing PCB/PCT)	NA	0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	NA	0
External electrical cables and cords	NA	0
Gas Discharge Lamps	NA	0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	NA	0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations. NA	0
Components and waste containing asbestos	NA	0
Components, parts and materials containing refractory ceramic fibers	NA	0
Components, parts and materials containing radioactive substances	NA	0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description T15 screw driver (Disassemble 3 pcs screws for MB and base pan)	T15 3.0~4.0 kgf-cm
Description Phillip screw driver (Disassemble 2 pcs screws for SSD,M.2 and MB)	+ 0.9~1.3 kgf-cm
Description Phillip screw driver (Disassemble 2 pcs screws for option board and MB)	+ 0.9~1.3 kgf-cm
Description Phillip screw driver (Disassemble 1 pcs screws for speaker and base pan)	+ 0.9~1.3 kgf-cm
Description T15 screw driver (Disassemble 3 pcs screws for heatsink and MB)	T15 2.5~3.5 kgf-cm
Description T15 screw driver (Disassemble 3 pcs screws for HDD cage and MB)	T15 2.5~3.5 kgf-cm
Description T15 screw driver (Disassemble 2 pcs screws for HDD connector and HDD cage)	T15 2.7~3.3 kgf-cm
Description Phillip screw driver (Disassemble 2 pcs screws for metal frame and HDD cage)	+ 0.9~1.3 kgf-cm

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Loosen the lock and slide the case..
2. Remove the hard disk.
3. Remove the metal frame by loosening 2 screws.(Phillip screwdriver)
4. Remove the cables by loosening 2 screws.(flathead or T15 screwdriver)
5. Remove the metal frame by loosening 3 screws.(flathead or T15 screwdriver)
6. Remove the fan..
7. Remove the memory.
8. Remove the heatsink by loosening 3 screws.(T15 screwdriver)
9. Remove the speaker by loosening 1 screw.(Phillip screwdriver)
10. Remove the PCB assembly by loosening 3 screws.(flathead or T15 screwdriver)
11. Remove the cable.
12. Remove non-recyclable material of the case.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1. Loosen the lock and slide the case.



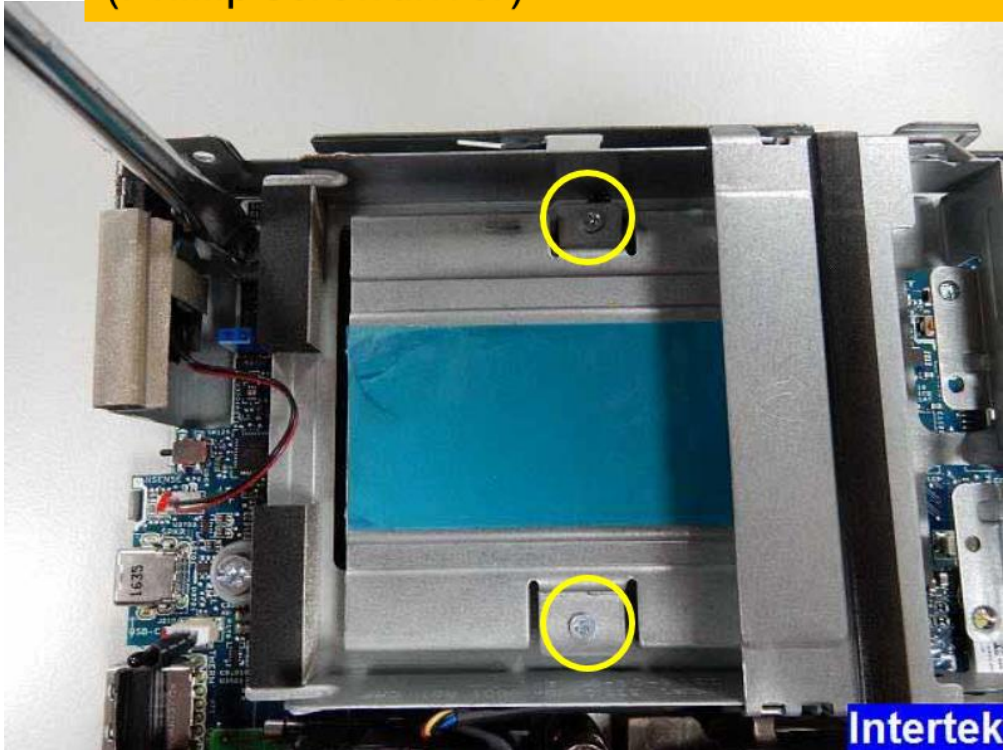
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2. Remove the hard drive.



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3. Remove the metal frame by loosening 2 screws.
(Phillip screwdriver)



4. Remove the cables by loosening 2 screws.
(flathead or T15 screwdriver)



5. Remove the metal frame by loosening 3 screws.
(flathead or T15 screwdriver)



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6. Remove the fan.



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7. Remove the memo



8. Remove the heatsink by loosening 3 screws.
(T15 screwdriver)



9. Remove the speaker by loosening 1 screw.
(Phillip screwdriver)



10. Remove the PCB assembly by loosening 3 screws. (flathead or T15 screwdriver)



11. Remove the cable



12. Remove non-recyclable material of the case.

